



NF372-TB FLUX-PEN®

Zero-Halogen, No-Clean Flux-Pen® for High Reliability Applications



Product Description

Kester NF372-TB Flux-Pen® is a zero-halogen, no-clean, low solids flux available as a Flux-Pen® for rework of conventional and surface mount circuit board assemblies. Kester NF372-TB flux passes IPC SIR testing in a raw or unheated state, ensuring Kester NF372-TB Flux-Pen®s can be safely used in rework applications, specifically those with high reliability requirements. NF372-TB Flux-Pen® residues are minimal, clear and non-tacky for improved cosmetics. NF372-TB Flux-Pen® is classified as ROL0 flux under IPC J-STD-004B.

Performance Characteristics:

- Zero-halogen (none intentionally added)
- Provides good solderability under air atmosphere
- Classified as ROL0 per J-STD-004B
- Pass SIR in raw state (unheated boards dried at 25°C/50%RH for 24 hours before test)
- Non-corrosive, non-conductive and non-tacky residues
- Compliant to GR-78-CORE (Telcordia/Bellcore)



RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive. Additional RoHS information is located at <https://www.kester.com/downloads/environmental>.



Physical Properties

Acid Number (typical):
16.6 mgKOH/gm

Specific Gravity @ 25°C: 0.793 (typical)

Solids Content (theoretical): 3.90 %



Reliability Properties

Copper Mirror: Low
J-STD-004B, IPC-TM-650, Method 2.3.32

Copper Corrosion: Low
J-STD-004B, IPC-TM-650, Method 2.6.15

Halogen Content: None detected
J-STD-004B, IPC-TM-650, Method 2.3.28.1

Electrochemical Migration (ECM):
Pass
J-STD-004B, IPC-TM-650, Method 2.6.14.1
Conditions: 65°C, 90% RH, 100V, 25days

Surface Insulation Resistivity (SIR):
Pass; [All Readings > 1.0x10⁸ Ω]
J-STD-004B, IPC-TM-650, Method 2.6.3.7
Conditions: 40°C, 90% RH, 12.5V, 7days

Surface Insulation Resistivity (SIR):
Pass
J-STD-004A, IPC-TM-650, Method 2.6.3.3
Conditions: 85°C, 85% RH, 100V, 7days

Bellcore SIR, IPC:
Pass; [All Readings >2.0x10¹⁰ Ω]
GR-78 13.1.3
Conditions: 35°C, 85% RH, 100V, 4days

Bono Corrosion Test:
Pass; [Fc = 0.5%]
Conditions: 85°C, 85% RH, 12V, 15days

Flux Application

NF372-TB Flux-Pen[®] is applied to circuit boards via Flux-Pen[®] for rework of printed wire assemblies.

Process Considerations

For best soldering performance, NF372-TB Flux-Pen[®] should only be applied to areas that will be fully heated by the soldering iron or other reflow tool. Care should be taken to avoid flooding the assembly. In cases of over application or incomplete heating, NF372-TB Flux-Pen[®] has passed SIR testing and has not contributed to corrosion.

Cleaning

NF372-TB Flux-Pen[®] residues are non-conductive, non-corrosive and do not require removal in most applications. If residue removal is required, it can be removed using commercially available flux residue cleaner. Contact Kester Technical Support for additional assistance.

Storage, Handling and Shelf Life

NF372-TB Flux-Pen[®] is flammable. Store away from sources of ignition. Shelf life is 2 years from the date of manufacture when handled properly and held at 10-25°C (50-77°F). The cap must be in place when not being used.

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at <https://www.kester.com/downloads/sds>.